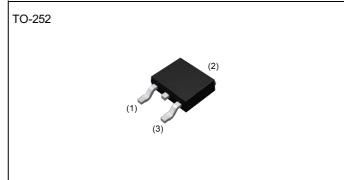
Nch 600V 4A Power MOSFET

V _{DSS}	600V
R _{DS(on)} (Max.)	1.43Ω
I _D	±4A
P _D	60W

_ _ _

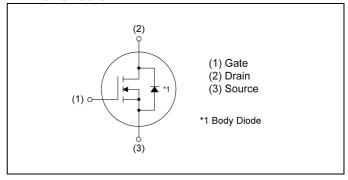
Outline



Features

- 1) Fast reverse recovery time (trr)
- 2) Low on-resistance
- 3) Fast switching speed
- 4) Drive circuits can be simple
- 5) Pb-free plating; RoHS compliant

•Inner circuit



Application

Switching

Packaging specifications

<u>_ </u>	
Packing	Embossed Tape
Packing code	TL1
Marking	R6004JND3
Quantity (pcs)	2500

● **Absolute maximum ratings** (T_a = 25°C ,unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain - Source voltage	V _{DSS}	600	V
Continuous drain current (T _c = 25°C)	I _D *1	±4	А
Pulsed drain current	I _{DP} *2	±12	А
Gate - Source voltage	V _{GSS}	±30	V
Avalanche current, single pulse	I _{AS} *3	1.0	А
Avalanche energy, single pulse	E _{AS} *3	52	mJ
Power dissipation (T _c = 25°C)	P _D	60	W
Junction temperature	T _j	150	°C
Operating junction and storage temperature range	T _{stg}	-55 to +150	°C

●Thermal resistance

Davamatav	Cymah al	Values			1.1:4
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - case	R_{thJC}	-	-	2.11	°C/W
Thermal resistance, junction - ambient	R _{thJA}	-	-	100	°C/W
Soldering temperature, wavesoldering for 10s	T _{sold}	-	-	265	°C

●Electrical characteristics (T_a = 25°C)

Darameter	Cumb al	Conditions	Values			Lloit	
Parameter 	Symbol	Conditions	Min.	Тур.	Max.	Unit	
Drain - Source breakdown voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = 1mA	600	-	-	V	
Zero gate voltage drain current	I _{DSS}	$V_{DS} = 600V, V_{GS} = 0V$ $T_j = 25^{\circ}C$	-	-	100	μA	
Gate - Source leakage current	I _{GSS}	$V_{GS} = \pm 30 V, V_{DS} = 0 V$	-	-	±100	nA	
Gate threshold voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 450 \mu A$	5.0	6.0	7.0	V	
Static drain - source on - state resistance	R _{DS(on)} *5	$V_{GS} = 15V, I_D = 2.0A$ $T_j = 25^{\circ}C$	-	1.10	1.43	Ω	
Gate resistance	R_{G}	f = 1MHz, open drain	-	3.6	-	Ω	

● Electrical characteristics (T_a = 25°C)

Dovometer	Cymah al	Conditions	Values			Linit
Parameter	Symbol	Symbol Conditions		Тур.	Max.	Unit
Input capacitance	C _{iss}	V _{GS} = 0V	-	260	-	
Output capacitance	C _{oss}	V _{DS} = 100V	-	18	-	
Reverse transfer capacitance	C _{rss}	C _{rss} f = 1MHz		0.9	-	_
Effective output capacitance energy related	$C_{o(er)}^{*6}$ $V_{GS} = 0V$		-	14	-	pF
Effective output capacitance time related	C _{o(tr)} *7	⁷ V _{DS} = 0V to 480V		50	-	
Turn - on delay time	t _{d(on)} *5	V _{DD} ≈ 300V, V _{GS} = 15V	-	13	-	
Rise time	t _r *5	I _D = 2.0A	-	11	-	no
Turn - off delay time	t _{d(off)} *5	$t_{d(off)}^{*5}$ $R_L \simeq 150\Omega$		24	-	ns
Fall time	t _f *5	$R_G = 10\Omega$	-	33	-	

● Gate charge characteristics (T_a = 25°C)

Darameter	Symbol Conditions -		Values			Unit
Parameter			Min.	Тур.	Max.	Offic
Total gate charge	Q_g^{*5}	V _{DD} ≈ 300V	-	10.5	-	
Gate - Source charge	Q _{gs} *5	I _D = 4A	-	3.0	-	nC
Gate - Drain charge	Q _{gd} *5	V _{GS} = 15V	-	3.5	-	
Gate plateau voltage	V _(plateau)	V _{DD} ≈ 300V, I _D = 4A	-	9.5	-	V

^{*1} Limited only by maximum temperature allowed.

^{*2} Pw ≤ 10µs, Duty cycle ≤ 1%

^{*3} L \simeq 100mH, V_{DD} = 50V, R_G = 25 Ω , starting T_i = 25°C

^{*4} Tc=25°C

^{*5} Pulsed

^{*6} Co(er) is a fixed capacitance that gives the same stored energy as Coss while V_{DS} is rising from 0 to 80% V_{DSS} .

^{*7} Co(tr) is a fixed capacitance that gives the same charging time as Coss while V_{DS} is rising from 0 to 80% V_{DSS} .

● Body diode electrical characteristics (Source-Drain) (T_a = 25°C)

Parameter	Symbol	Conditions	Values			Unit	
- Farameter	Symbol	Conditions	Min.	Тур.	Max.	Offic	
Source current	I _S *1	- T _C = 25°C	1	-	4	Α	
Pulsed source current	l _{SP} *2	1C - 23 C	1	-	12	Α	
Source-Drain voltage	V _{SD} *5	$V_{GS} = 0V$, $I_S = 4A$	-	-	1.7	V	
Reverse recovery time	t _{rr} *5		-	45	-	ns	
Reverse recovery charge	Q _{rr} *5	I _S = 4A di/dt = 100A/µs	-	100	-	nC	
Peak reverse recovery current	_{rr} *5		-	4.0	-	Α	

Fig.1 Power Dissipation Derating Curve

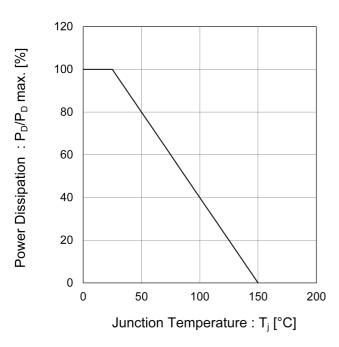


Fig.2 Drain Current Derating
Curve vs. Junction Temperature

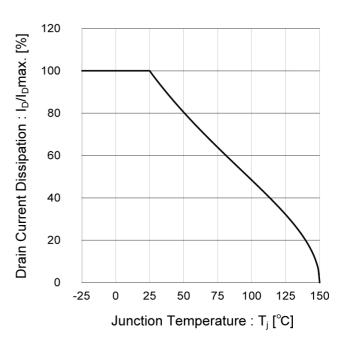


Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

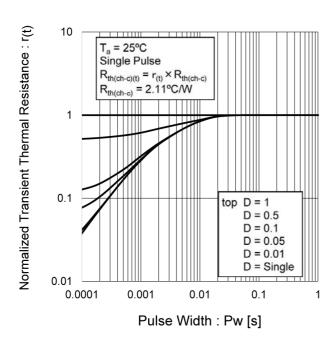
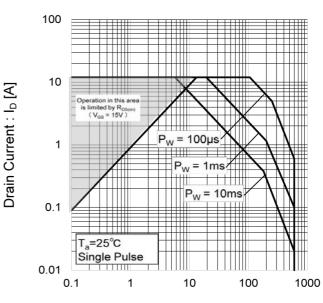


Fig.4 Maximum Safe Operating Area



Drain - Source Voltage: V_{DS} [V]

5/11

Fig.5 Avalanche Energy Derating
Curve vs. Junction Temperature

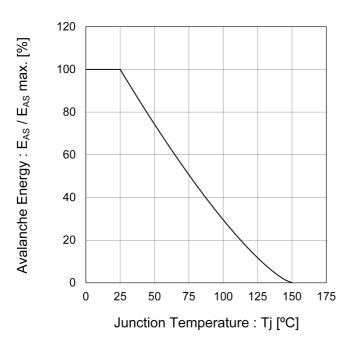


Fig.6 Normalized Breakdown Voltage vs. Junction Temperature

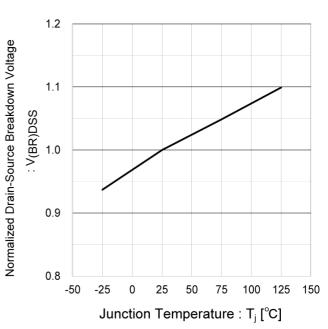


Fig.7 Typical Output Characteristics(I)

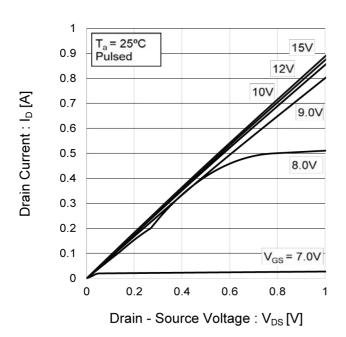
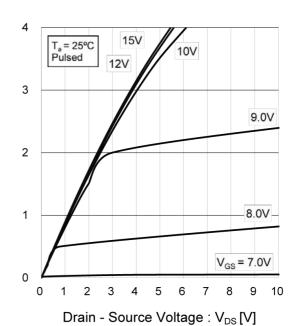


Fig.8 Typical Output Characteristics(II)



Drain Current : I_D [A]

Fig.9 Typical Transfer Characteristics

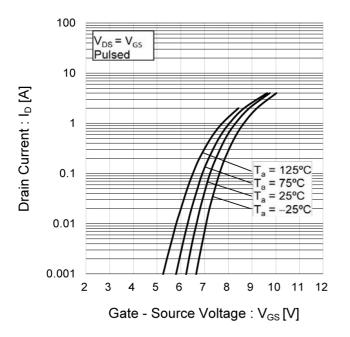


Fig.10 Normalized Gate Threshold .

Voltage vs Junction Temperature

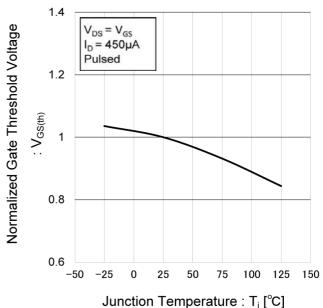


Fig.11 Static Drain - Source On - State Resistance vs. Gate Source Voltage

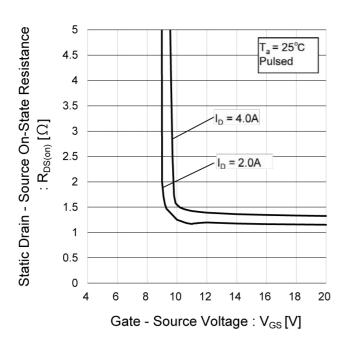


Fig.12 Normalized Static Drain - Source On - State Resistance vs. Junction Temperature

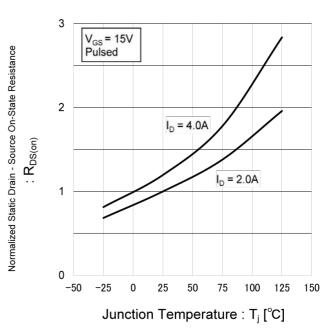


Fig.13 Static Drain - Source On - State Resistance vs. Drain Current

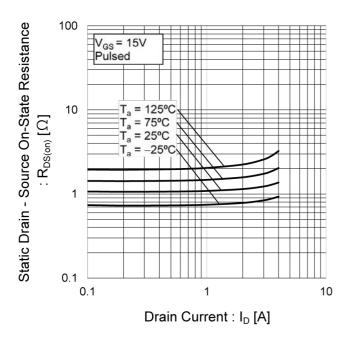


Fig.14 Typical Capacitance vs.
Drain - Source Voltage

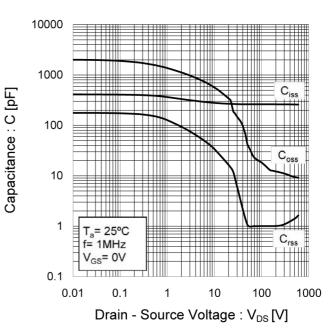


Fig.15 Typical Coss Stored Energy

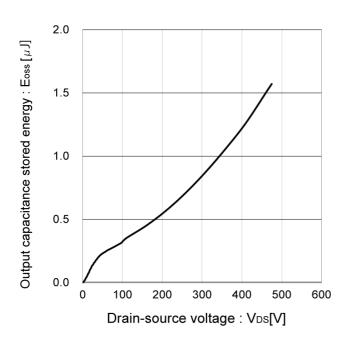
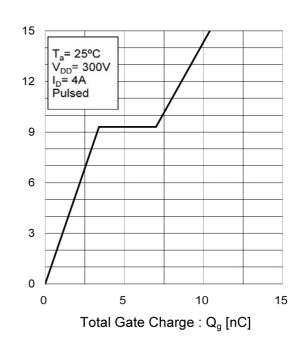


Fig.16 Typical Gate Charge



Gate - Source Voltage : V_{GS} [V]

Fig.17 Inverse Diode Forward Current vs. Source - Drain Voltage

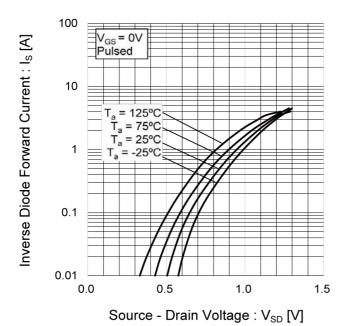
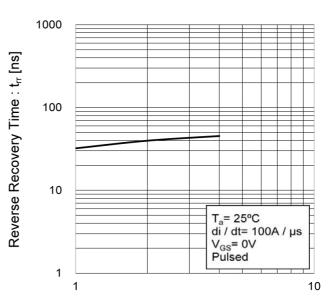


Fig.18 Reverse Recovery Time vs.
Inverse Diode Forward Current



Inverse Diode Forward Current: I_S [A]

Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

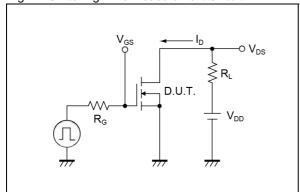


Fig.2-1 Gate Charge Measurement Circuit

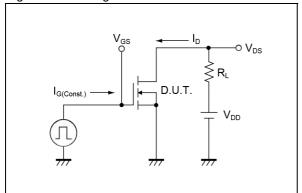


Fig.3-1 Avalanche Measurement Circuit

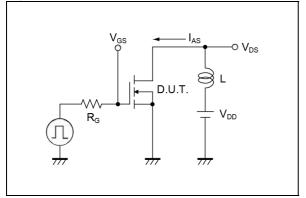


Fig.4-1 Diode Recovery Measurement Circuit

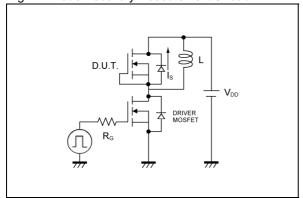


Fig.1-2 Switching Waveforms

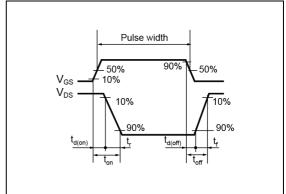


Fig.2-2 Gate Charge Waveform

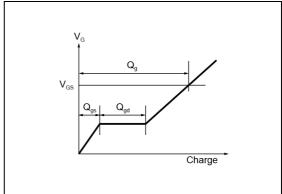


Fig.3-2 Avalanche Waveform

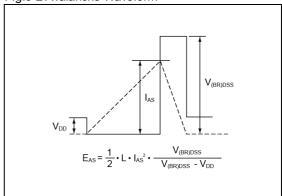
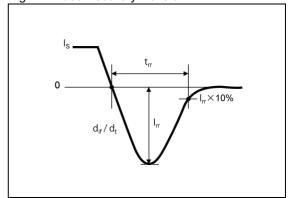
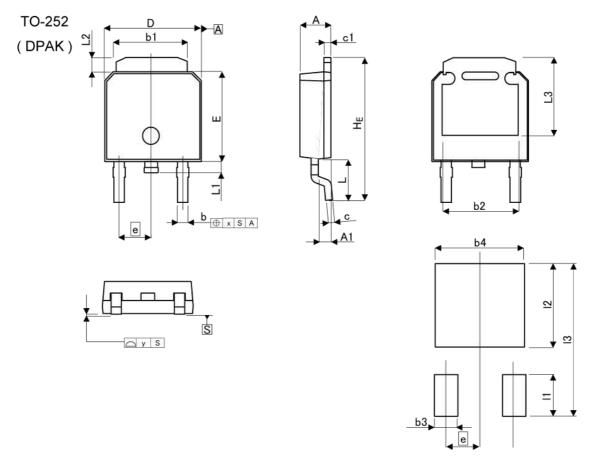


Fig.4-2 Diode Recovery Waveform



Dimensions



Pattern of terminal position areas [Not a recommended pattern of soldering pads]

DIM -	MILIME	ETERS	INC	HES
DIIVI	MIN	MAX	MIN	MAX
Α	2.20	2.40	0.087	0.094
A1	0.70	1.10	0.028	0.043
b	0.60	0.90	0.024	0.035
b1	5.20	5.50	0.205	0.217
b2	5.	35	0.2	211
С	0.40	0.60	0.016	0.024
c1	0.40	0.60	0.016	0.024
D	6.40	6.80	0.252	0.268
е	2.	30	0.091	
E	6.00	6.40	0.236	0.252
HE	9.40	10.40	0.370	0.409
L	2.	70	0.1	06
L1	0.60	1.00	0.024	0.039
L2	0.70	1.30	0.028	0.051
L3	5.	30	0.2	209
x	(4)	0.25	Q .	0.010
У	(7.)	0.10	-	0.004

DIM	MILIMETERS		INC	HES
DIIVI	MIN	MAX	MIN	MAX
b3	727	1.15	2	0.045
b4	-	5.55	8	0.219
11	F2//	2.77	2	0.109
12	1 4. 3	5.50	-	0.217
13	4	10.40	2	0.409

Dimension in mm/inches



Notice

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JAPAN	USA	EU	CHINA
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CLASSIV	CLASSIII	CLASSⅢ	CLASSIII

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 - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
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 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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